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Appl. No. 09/925,740
Amdt. Dated September 2, 2004
Reply to Office Action of June 2, 2004

Listing of Claims:

- 1-4. (Canceled)
5. (Currently amended) A process for producing a copper clad laminate comprising, providing an insulation layer constituent material having a first and a second side, coating said first side with a first copper foil of a first thickness, coating said second side with a second copper foil of a second thickness to produce an insulation layer constituent material, first copper foil and second copper foil assembly, wherein the thickness of said second foil is greater than the thickness of said first foil, hot pressing said assembly to produce said laminate, wherein said first copper foil is not recrystallized during said hot pressing, and wherein said second copper foil is recrystallized during said hot pressing.
6. (Previously presented) The process of claim 5, wherein the thickness of the second foil is four times or less than the thickness of the first foil.
7. (Previously presented) The process of claim 5, wherein said insulation layer constituent material is a resin.
8. (Previously presented) The process of claim 5, wherein said second copper foil contracts about 0.05% under pressing conditions of 180°C and 1hr.
9. (Currently amended) The process of claim 5, wherein said second copper foil is a S-HTE foil.

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10. (Previously presented) The process of claim 5, wherein, after hot pressing, the Young's modulus of said first copper foil is 1.1 times more than the Young's modulus of said second copper foil.
11. (Currently amended) A process for producing a copper clad laminate comprising, providing an insulation layer constituent material having a first and a second side, coating said first side with a first copper foil of a first thickness, coating said second side with a second copper foil of a second thickness to produce an insulation layer constituent material, first copper foil and second copper foil assembly, wherein the thickness of said second foil is greater than the thickness of said first foil, hot pressing said assembly to produce said laminate, wherein said first and second copper foils are recrystallized during said hot pressing, wherein said second copper foil is more recrystallized than said first copper foil.
12. (Previously presented) The process of claim 11, wherein the thickness of the second foil is four times or less than the thickness of the first foil.
13. (Previously presented) The process of claim 11, wherein said insulation layer constituent material is a resin.
14. (Previously presented) The process of claim 11, wherein said second copper foil contracts about 0.05% under pressing conditions of 180°C and 1hr.
15. (Currently amended) The process of claim 11, wherein said second copper foil is a ~~S-THE~~ S-HTE foil.

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16. (Previously presented) The process of claim 11, wherein, after hot pressing, the Young's modulus of said first copper foil is 1.1 times more than the Young's modulus of said second copper foil.
17. (Previously presented) A process for producing a copper clad laminate, providing an insulation layer constituent material having a first and a second side, coating said first side with a first copper foil of a first thickness, coating said second side with a second copper foil of a second thickness to produce an insulation layer constituent material, first copper foil and second copper foil assembly, wherein the thickness of said second foil is greater than the thickness of said first foil, hot pressing said assembly to produce said laminate, wherein said first and second copper foil contract during said hot pressing, wherein said second copper foil contracts to a larger extent than said first copper foil during said hot pressing.
18. (Previously presented) The process of claim 17, wherein the thickness of the second foil is four times or less than the thickness of the first foil.
19. (Previously presented) The process of claim 17, wherein said insulation layer constituent material is a resin.
20. (Previously presented) The process of claim 17, wherein said second copper foil contracts about 0.05% under pressing conditions of 180°C and 1hr.
21. (Currently amended) The process of claim 17, wherein said second copper foil is a ~~S-THE~~ S-HTE foil.

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22. (Previously presented) The process of claim 17, wherein, after hot pressing, the Young's modulus of said first copper foil is 1.1 times more than the Young's modulus of said second copper foil.

23-29. (Canceled)